

COMPASS Munich 2019

Call For Papers

FormFactor would like to invite you to submit an abstract to our users' conference on November 14th, 2019 in Munich, Germany. COMPASS will provide a forum to share test and measurement techniques and to exchange best practices and experiences using FormFactor's on-wafer test and measurement products.

Each session consists of a **25-minute presentation** and 10 minutes of Q&A at the end. There is **no formal (written) technical paper required to submit**, A summary of the proceedings will be publicized, and **an electronic version of the presentations will be made available to all attendees**.

If you are interested in presenting, please submit your **200-word abstract by August 26th, 2019 to compass@formfactor.com** Include the following with your abstract submission:

- Your name and contact information
- Company name
- Presentation title

FormFactor is soliciting presentations for the following topics, which include (but are not limited to):

Potential Topics:

- Test challenges with automotive ICs
- RF/mmW/THz measurement and calibration methodology – technology trends and theory
- High-voltage and high-current on-wafer device characterization
- Dynamic measurement challenges (e.g. current collapse measurements or unclamped inductance switching)
- Mass data acquisition for statistical data collection – automation strategies and integration
- Unattended over-temperature measurements – dealing with challenges, suggested guidelines and solutions
- Small pad probing – procedures, guidelines, solutions
- 3D-TSV RF characterization
- Wafer- and/or package-level reliability test
- Integrated measurement systems – requirements, architecture and application examples such as power and wafer-level reliability
- Procedures or criteria to define a proper system for data correlation between engineering and production test
- Tips, techniques and utilities for dealing with challenging probing situations
- DC parametric test
- Instrument drift and calibration
- MEMS device characterization
- Cryogenic probing
- Magnetic device probing
- Hall effect
- Maintenance of on-wafer engineering probes
- Silicon photonics testing (micro-LED/VCSEL, parallel test)

Additional Topics:

- Test challenges with automotive ICs
- RF calibration – innovative techniques for accurate production test
- 40+ GHz test including automotive radar, cell phone short haul/backhaul, 802.11ad
- HB-LED high-volume test
- Silicon photonics testing (micro-LED/VCSEL, parallel test)
- High-power production test
- Prolonging probe card life – maintenance and cleaning procedures; evaluation of new cleaning media
- Cost-of-ownership models
- 3D package test at high volume
- Production test over temperature
- Micro-bump production probing (such as 3D-TSV)
- Production test methodologies
- Data transition and correlation procedures from R&D to production test
- Data comparison between different probing technologies
- WL-CSP and other package test with probes
- PTPA error analysis – small pads, over temperature, probe card error, prober error, wear, etc.
- Probe card metrology tools
- Probe cards for PAs and LNAs - matching networks, low inductance
- The future of test
- Over travel vs contact resistance

Important Dates:

- Abstract submissions due: **Monday, August 26th**
- Acceptance notification: by **Friday, August 30th**
- Draft presentation files due: **Friday, October 18th**
- Final review with Technical Committee: by **Friday, October 25th**
- Final presentation files due: Friday, **November 8th**
- COMPASS presentation: Thursday, **November 14th**

For questions, please contact our COMPASS 2019 Technical Committee Chairs:

- Arne Holland, FormFactor, Inc.: arne.holland@formfactor.com
- Jens Klattenhoff, FormFactor, Inc.: jens.klattenhoff@formfactor.com
- Peter Andrews, FormFactor, Inc.: peter.andrews@formfactor.com